

# Data Sheet



## SCP1000 SERIES (120 kPa) ABSOLUTE PRESSURE SENSOR

### Features

- 30 kPa - 120 kPa measuring range
- Single +2.4 ... 3.3 V supply
- Four measuring modes plus power down mode
- On-chip linearization and temperature compensation
- On-chip temperature measurement
- Pre-programmed calibration coefficients, temperature offset and sensitivity coefficients in the EEPROM
- Standard digital output: SPI or I<sup>2</sup>C<sup>(1)</sup>
- Small package size with optional<sup>(2)</sup> sealing gasket. Diameter 6.1 mm, height 1.7 mm
- Proof pressure 3.2 MPa
- Pb-free solderable component & RoHS-compatible

### Applications

- Barometric pressure measurement and altimeter applications
- Home weather stations
- Advanced medical applications
- Level gauging

### Benefits

- 1.5 Pa (10cm) resolution with < 10 μA current consumption
- Altimeter/barometer function can be realized with minimum use of MCU
- Chemically and mechanically robust package
- Sensor based on the proven VTI 3D-MEMS Technology

### Ordering Information

Product	Description
SCP1000-D01	30 kPa - 120 kPa, SPI interface, internal clock
SCP1000-D11	30 kPa - 120 kPa, I <sup>2</sup> C interface, internal clock

### Absolute Maximum Ratings

Parameter	Value	Unit
Supply voltage (Vdd)	-0.3 to +3.6	V
Voltage at input / output pins <sup>(3)</sup>	-0.3 to (Vdd + 0.3)	V
ESD (Human Body Model)	±2.0	kV
ESD (Charged Device Mode)	±0.5	kV
Storage temperature	-30 ... +85	°C
Proof pressure	3.2	MPa

Note 1 I<sup>2</sup>C compatible TWI (Two Wire Interface)

Note 2 VTI's I-seal gasket

Note 3 Referred to DVDD

## Electrical Characteristics

Vdd = 2.7 V and ambient temperature unless otherwise specified

Parameter	Condition	Min.	Typ.	Max.	Units
Supply voltage Vdd		2.4		3.3	V
Current Consumption	High resolution mode		26	50	μA
	high speed mode		25	50	μA
	ultra low power mode		3.5	6	μA
	power down		200	500	nA
Output Load	@ 500 kHz			50	pF
Digital Pins Input Capacitance				1.6	pF
SPI Clock Frequency				500	kHz
I <sup>2</sup> C Clock Frequency				400	kHz
Data Transfer Time	@ 500 kHz		120		μs

## Performance Characteristics

Parameter	Condition	Min.	Typ.	Max.	Units
Operating Pressure Range	Nominal	30		120	kPa
Operating Temperature		-20		+70	°C
Absolute Pressure Accuracy <sup>(4)</sup>	Sea level, +10 °C ... +40 °C	-100		100	Pa
		-8.5		8.5	m
Relative Accuracy	0 ... 3000m, +10 °C...+40 °C	-100	±27	100	Pa
		-8.5	2	8.5	m
	0 ... 8000m, -20°C...+70°C <sup>(5)</sup>	-250	±100	250	Pa
		-40	8.5	40	m
Resolution	High resolution mode, 0 ... 3000m		1.5	6	Pa
			0.10	0.4	m
	Ultra low power mode, 0 ...3000m		2	15	Pa
			0.20	1.3	m
Non-linearity	0 ... 3000 m			25	Pa
				1	m
Digital pressure output data word length				19	bits
Digital temperature output data word length				14	bits
Pressure data output refresh rate	High resolution mode		2		Hz
	High speed mode		9		Hz
Temp. Resolution			0.2	0.5	°C
Temp. Accuracy		-2	1	+2	°C

Note 4 After offset adjustment at one pressure point

Note 5 Conservative estimate

## Interface Options

The communication interface is pre-programmed in the factory and can be either SPI (Serial Peripheral Interface) or I<sup>2</sup>C (Inter-Integrated Circuit). The SPI interface is a full duplex 4 wire interface and the connection between the MCU and SCP1000 is achieved using MOSI, MISO, SCK and CSB. The I<sup>2</sup>C interface is a slave-only half duplex two-wire interface available via the SDA and SCL pins.

## Interface Options

The SCP1000 Pressure sensor has 4 normal operation modes plus power down mode.

Mode	Pressure measurement	Resolution	Output data refresh rate
High resolution	Continuous	17 bits	2 Hz
High speed	Continuous	15 bits	9 Hz
Ultra low power	Periodical	15 bits	Approximately 1 Hz
Low power	External trigger	17 bits or 15 bits	
Power Down	Activated through PD pin		

## Electrical Connections

The SCP1000 pressure sensor supports two communications interfaces, SPI and I<sup>2</sup>C. The appropriate communications interface is pre-programmed in the factory.

### SCP1000- D01 (SPI Interface)

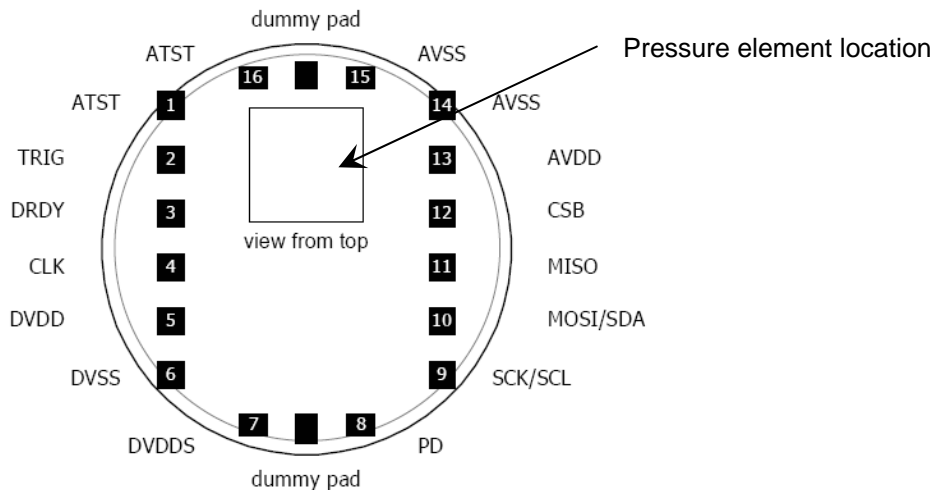
Pin #	Name	Function	Characteristics
1	ATST	Not used	Used only in manufacturing tests. To be connected to AVSS in normal operation
2	TRIG <sup>6</sup>	Trigger input	Digital input
3	DRDY	Interrupt signal (data ready)	Digital output
4	CLK	Not used, connect to GND	
5	DVDD	Digital supply voltage	Power line
6	DVSS	Digital ground	Power line
7	DVDDS	Digital supply filter	Digital power supply filter
8	PD <sup>6</sup>	Power down	Input to force the chip in power down mode
9	SCK <sup>6</sup>	SPI clock input	Interface clock
10	MOSI <sup>6</sup>	SPI data input	SPI – data input
11	MISO <sup>6</sup>	SPI data output	Digital data output
12	CSB <sup>6</sup>	SPI chip select	Digital input
13	AVDD	Analog supply voltage	Power line
14	AVSS	Analog ground	Power line
15	AVSS	Analog ground	Power line
16	ATST	Not used	Used only in manufacturing tests. To be connected to AVSS in normal operation

Note 6 The MCU has to actively drive the signal in high and low states

### SCP1000- D11 (I<sup>2</sup>C Interface)

Pin #	Name	Function	Characteristics
1	ATST	Not used	Used only in manufacturing tests. To be connected to AVSS in normal operation
2	TRIG <sup>6</sup>	Trigger input	Digital input
3	DRDY	Interrupt signal (data ready)	Digital output
4	CLK <sup>6</sup>	Not used, connect to GND	
5	DVDD	Digital supply voltage	Power line
6	DVSS	Digital ground	Power line
7	DVDDS	Digital supply filter	Digital power supply filter
8	PD <sup>6</sup>	Power down	Input to force the chip in power down mode
9	SCL <sup>6</sup>	I <sup>2</sup> C serial clock	Interface clock
10	SDA <sup>6</sup>	I <sup>2</sup> C data	I <sup>2</sup> C data input/output
11	MISO	n/c	n/c
12	CSB	n/c	n/c
13	AVDD	Analog supply voltage	Power line
14	AVSS	Analog ground	Power line
15	AVSS	Analog ground	Power line
16	ATST	Not used	Used only in manufacturing tests. To be connected to AVSS in normal operation

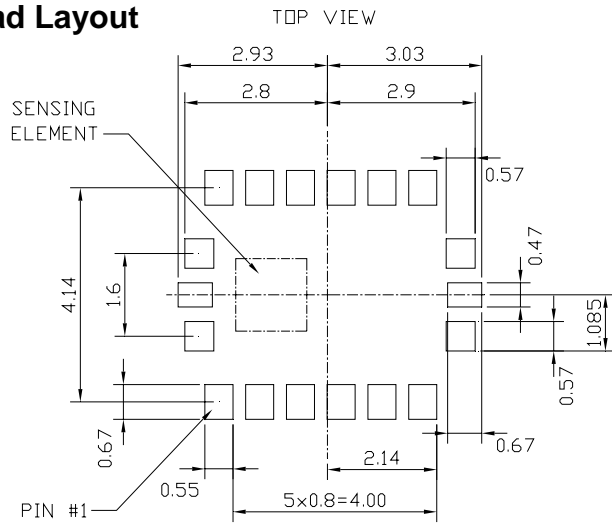
Note 6 The MCU has to actively drive the signal in high and low states



**Figure 1** Pin arrangement of SCP1000

**Note:** In order to ensure the contact reliability, both pins in the pin pairs 1,16 and 14,15 (which are internally connected together) should be soldered.

**PCB Pad Layout**



**Dimensions**

